FBFH SERIES

Ferrite Bead (EMI 5-Hole)

贴片穿孔磁珠

Ferrite Bead (EMI 5-Hole)

特性

Characteristics

低直流电阻

Low DC resistance

特殊的NiSn焊盘可改善焊接效果

Special NiSn pad for improved soldering results

阻抗高达580 Ω

Impedance up to 580 Ω

应用

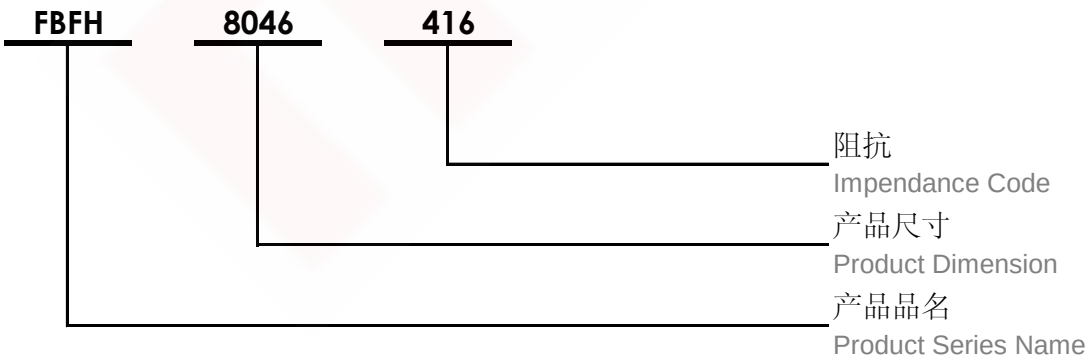
Application

防止PCB组件的射频干扰

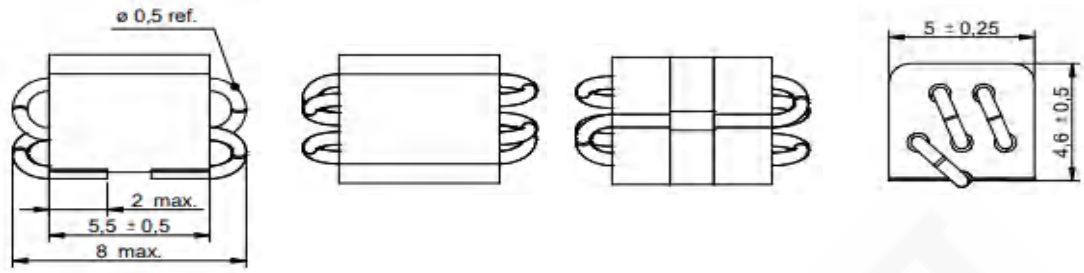
Protection against radio frequency interferences of components on PCB's

产品品名介绍

Product Number Structure



尺寸
Dimension (mm)



焊盘推荐
Land Pattern Recommended (mm)

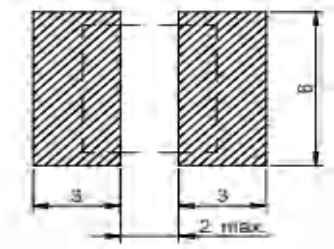


示意图
Schematics

电性特性
Electrical Properties

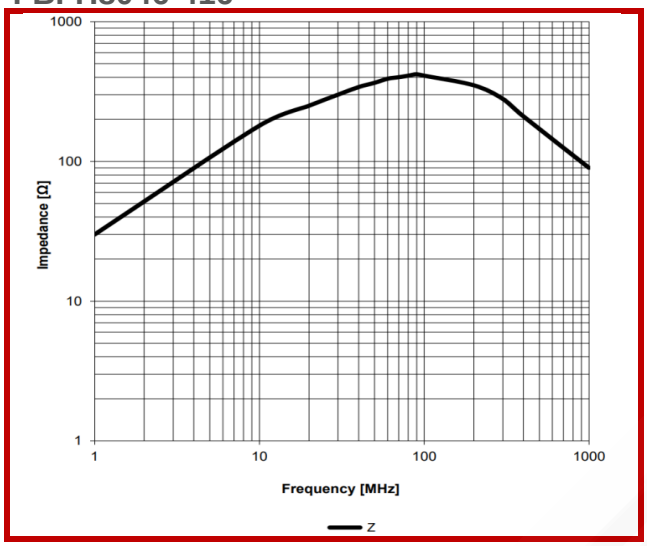
型号 Part No.	阻抗 Impedance Z (Ω) ±25%	温升电流 Rated Current IR 40°C max (A)	直流电阻 DCResistance DCRmax (mΩ)	固化温度 Curie Temperature Tc °C	卷盘数量 Taping Reel Qty. pcs
FBFH8046-416	@25 MHz 272 @100 MHz 416	5.00	11.00	140	1,000

测试状态
Test Condition

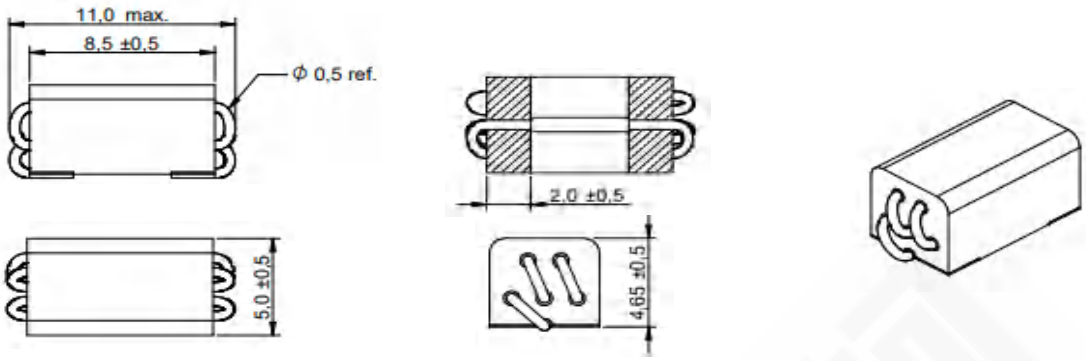
☆ 工作温度：-40°C ~ +125°C
Operating Temperature: -55°C ~ +125°C

典型阻抗特性
Typical Impedance Characteristics

FBFH8046-416



尺寸
Dimension (mm)



焊盘推荐
Land Pattern Recommended (mm)

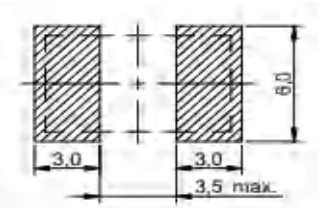


示意图
Schematics

电性特性
Electrical Properties

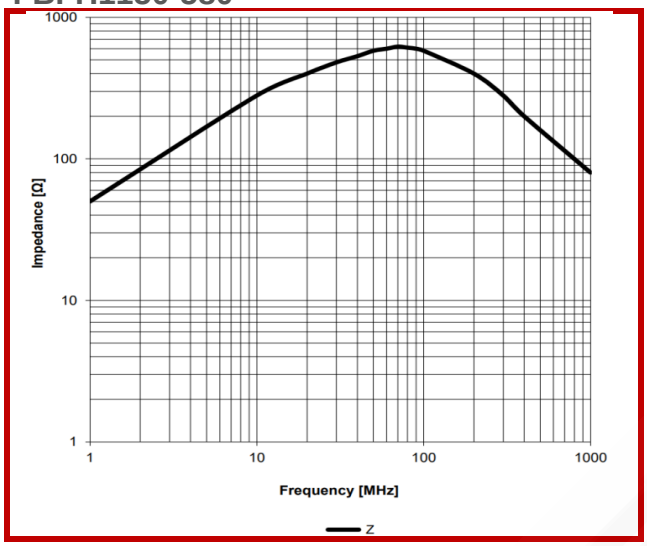
型号 Part No.	阻抗 Impedance Z (Ω) ±25%	温升电流 Rated Current IR 40°C max (A)	直流电阻 DCResistance DCRmax (mΩ)	固化温度 Curie Temperature Tc °C	卷盘数量 Taping Reel Qty. pcs
FBFH1150-580	@25 MHz 425 @100 MHz 580	5.00	12.00	140	1,000

测试状态
Test Condition

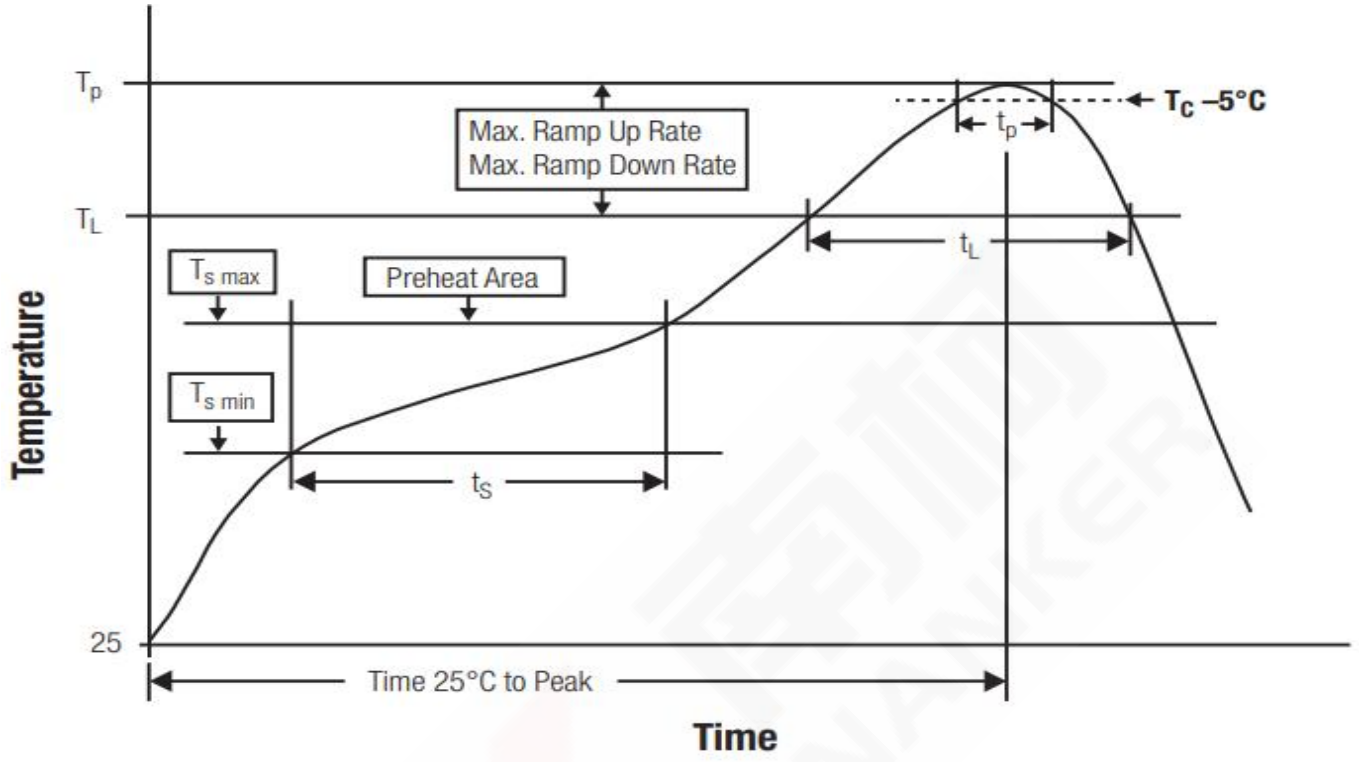
☆ 工作温度：-40°C ~ +125°C
Operating Temperature: -55°C ~ +125°C

典型阻抗特性
Typical Impedance Characteristics

FBFH1150-580



回流焊曲线图
Classification Reflow Profile for SMT Components



封装体峰值温度(Tp)分类
Classification Reflow Soldering Profile:

	封装厚度 Package Thickness	封装体积 Package Volume		
		<350 mm^3	350~2,000 mm^3	>2,000 mm^3
无铅装配 PB-Free Assembly	<1.60mm	260°C	260°C	260°C
	1.60~2.50mm	260°C	250°C	245°C
	>2.50mm	260°C	245°C	245°C

- 回流焊参照标准 IPC/JEDEC J-STD-020D。
  Reflow is refer to standard IPC/JEDEC J-STD-020D.